

Please add the following as the last full paragraph on Page 37:

While the invention has been particular shown and described in reference to preferred embodiments thereof, it will be understood by those skilled in the art that changes in form and details may be made therein without departing from the spirit and scope of the invention.\

IN THE CLAIMS:

Please amend claim 12, as follows:

12. (Amended) A mask according to claim 10, wherein said blight pattern is regularly arranged.

Please amend claim 13, as follows:

13. (Amended) A mask according to Claim 10, wherein said blight pattern is irregularly arranged.

Please cancel claims 1-5, and 14-23 without prejudice or disclaimer.

Please add new claims 24 to 35, as follows:

24. (NEW) An exposure method comprising:
a projection optical system which projects an image of a mark on a mask onto a substrate to form an alignment mark on said substrate; and

a

an alignment sensor which detects said alignment mark formed on said substrate,
wherein said alignment mark includes a plurality of first patterns having a height and a
second pattern for preventing a film covering the alignment mark from being depressed.

²⁰
~~25~~. (NEW) An exposure apparatus comprising:

a projection optical system which projects an image of a mark on a mask onto a
substrate to form an alignment mark on said substrate; and

an alignment sensor which detects said alignment mark formed on said substrate,
wherein said alignment mark includes a plurality of sub-patterns which are arranged
one by one with a predetermined interval therebetween, said sub-patterns including a plurality of
concave patterns.

⁵
~~26~~. (NEW) An exposure method comprising:

using the mask as set forth in Claim ¹~~6~~ and forming an alignment mark on said substrate by
projecting an alignment mark on said mask onto said substrate.

⁶
~~27~~. (NEW) An exposure apparatus for exposing a substrate by projecting a pattern on a mask
onto the substrate, comprising:

a mask holding member which holds the mask as set forth in Claim ¹~~6~~, and

a projection system which projects an alignment mark on the mask onto the substrate.

¹¹
~~28.~~ (NEW) An exposure method comprising:

using the mask as set forth in Claim ⁷~~10~~ and forming an alignment mark on said substrate by projecting an alignment mark on said mask onto said substrate.

^{12.}
~~29.~~ (NEW) An exposure apparatus for exposing a substrate by projecting a pattern on a mask onto the substrate, comprising:

a mask holding member which holds the mask as set forth in Claim ⁷~~10~~, and
a projection system which projects an alignment mark on the mask onto the substrate.

^{14.}
~~30.~~ (NEW) An exposure apparatus according to claim ¹³~~24~~, wherein the distance between each of a plurality of said second patterns is less than resolution of said alignment sensor.

^{15.}
~~31.~~ (NEW) An exposure apparatus according to claim ¹⁴~~30~~, wherein said second patterns are regular.

^{16.}
~~32.~~ (NEW) An exposure apparatus according to claim ¹⁴~~30~~, wherein said second patterns are irregular.

^{17.}
~~33.~~ (NEW) An exposure apparatus according to claim ¹³~~24~~, wherein the distance between adjacent first patterns is equal to or more than $2\mu\text{m}$.

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TOP SECRET

Preliminary Amendment
August 16, 2001

Divisional of Appln. No. 09/476,208

¹⁸
~~24~~ (NEW) An exposure apparatus according to claim ¹³~~24~~, wherein said alignment sensor includes an alignment system of an image processing type which picks up an image of said alignment mark to measure the position of said alignment mark.

A30 ¹⁹
~~35~~ (NEW) An exposure apparatus according to claim ¹³~~24~~, wherein said alignment sensor includes an alignment system of an interference type which measures the position of said alignment mark by using interference of light from said alignment mark.

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